



ADVANCED PROGRAM AND REGISTRATION FORM

19th European Advanced Technology Workshop on Micropackaging and Thermal management

25th & 26th March 2026

MERCURE VIEUX PORT



Quai Louis Prunier 17000 La Rochelle - France
Tel: 33 (0) 5 46 50 61 50
Email: H0569@accor.com.

Hotel reservations will be made by the
organizing committee

Workshop arrival day:
Tuesday, 24th March 2026

Sponsored by



WORKSHOP COMMITTEE:

Conference chairmen:

France:

Jean-Yves SOULIER (Safran Data Systems)
Jean-Pierre FRADIN (ICAM Toulouse)
Bruno LEVRIER (BL Expertises)
Alexandre VAL (Valeo)

Technical Program Committee:

France:

Sandrine LELONG-FENEYROU (Safran Data Systems)
Raphael SOMMET (XLIM – Limoges University)
Vincent AYEL (PPRIME Institute, CNRS-ENSMA- Poitiers University)
Mohamad ABO RAS (NANOTEST)

Germany:

Thomas HARDER (ECPE)

Poland:

Boguslaw WIECEK (Łódź University of Technology, Institute of Electronics)

USA:

Dave SAUMS (DS&A LLC)

Thermal management remains a crucial constraint in electronics packaging and is a mandatory aspect in every industry – aerospace, automotive, consumer, industrial, military - technology roadmap worldwide.

The upcoming workshop will present some latest improvements in thermal management solutions at system level, in power electronics, in materials, in modelling and in techniques for characterizing and testing materials. It will also present some innovative cooling solutions such as two-phase technologies and liquid cooling.

Organized by:

International Microelectronics Assembly and Packaging Society France
17 rue de l'Amiral Hamelin 75016 Paris, France
E-mail : imaps.france@orange.fr

CONFERENCE SCHEDULE

DAY 1 - 25th March 2026 (Wednesday)

08:10 am	Opening address & table tops presentation Jean-Yves Soulier, Conference chairman & IMAPS France Treasurer
08:15 am	KEYNOTE: Thermal management of wide-bandgap power semiconductor devices C. Buttay CNRS, INSA de Lyon, Université Claude Bernard Lyon 1 (France)
08:45 am – 09:40 am	SESSION 1: COOLING AT SYSTEM LEVEL Chairs: B. Levrier, D. Saums Introduction of liquid metal for highly dissipative processors for space applications H. Garcia Thales Alenia Space (France) Thermal Characterization and Environmental Qualification of Oscillating Heat Pipes in VITA 48.2 Conduction Cooled Assemblies C. Wilson ThermAvant Technologies (USA)
09:40 am -10:10 am	Coffee Break / Table Top Exhibition
10:10 am – 12:00 am	SESSION 2: MATERIALS Chairs: A. Val, P. Couderc New Sintering Materials: From Slit-Nozzle-Dispensing for Large Substrates down to Jet Dispensing for small Diodes Dr. A. Stelzer, Dr. B. Rábay Nano-Join (Germany) Liquid metal TIMs for AI ASIC cooling K. Vijay, M. Lazić Indium (USA) Aluminum–silicon alloys with tailored thermophysical properties for electronic’s cooling using silicon from photovoltaic waste C. Vladu, E. Neubauer RHP Technology (Austria) Diamond potting A. De Bibikoff, M. Tavares Safran Data Systems (France)
12:00 am – 01:30 pm	Lunch
01:40 pm – 03:00 pm	SESSION 3: MODELING & SIMULATIONS Chairs: JP. Fradin, JY. Soulier Numerical study of PCM-copper foam composite for power electronics thermal management for different geometries and heat-flux density conditions T. Lemonnier (1,2), H. Lescot (2), R. Rullière (1), C. Buttay (3) (1) INSA Lyon, (2) Renault Group, (3) CNRS UMR5005 Optimization of Power module geometries for EV charging J. Helie (1), Federico Ghioldi, Federico Piscaglia (2), Alexandre Marie, Jean-Pierre Fradin (3) (1) Schaeffler (France), (2) Politecnico di Milano (Italy), (3) ICAM (France) Transient Multiphysics Simulation of TVS Diodes D. Frigerio (1), T. Bertoncelli, O. Ilina (2) (1) Synopsys (Italy), (2) Synopsys (Germany)

03:05 pm – 04:30 pm

SESSION 4: 2-PHASE COOLING
Chairs: V. Ayel, B. Levrier

Optimization of capillary mesh for thermal systems using additive manufacturing: exploration of design through different manufacturing strategies

[D. Serret](#)
TEMISTh (France)

03:30 pm – 04:00 pm

Coffee Break / Table Top Exhibition

Overview for Electronics: Liquid Immersion and Pumped Two-Phase Dielectric Fluid Cooling

[D. Saums](#)
DS&A LLC (USA)

04:30 pm – 05:55 pm

SESSION 5: CHARACTERIZATION & TESTS
Chairs: JP. Fradin, M. Sabah

Effect of Surface Roughness on the Thermal and Reliability Performance of Thermal Interface Materials

[A. Reinke](#), [A. Harder](#), [S. Campos-Böttges](#), [P. Zimon](#), [T. Bräuer](#), [M. Abo Ras](#)
Berliner Nanotest und Design GmbH (Germany)

Understanding the measurement of the temperature in GaN HEMTs : Overview of measurement techniques and results

[M. Boussekri](#), [J-C. Nallatamby](#), [R. Sommet \(1\)](#), [K. Karrame \(2\)](#), [C. Chang \(3\)](#)
(1) XLIM, (2) ICAM (3) UMS (France)

Thermal Investigations of GaN layers on foreign substrates for vertical power devices
[L. Mitterhuber](#), [V. Leitgeb](#), [B. Kosednar-Legenstein](#), [E. Kraker \(1\)](#), [F. Brunner](#), [E. Bahat-Treidel \(2\)](#)

(1) Materials for Microelectronics, Materials Center Leoben Forschung GmbH, Leoben, (Austria),
(2) Ferdinand-Braun-Institute Berlin (Germany)

05:55 pm

End of 1st day Sessions / Tabletop Exhibition

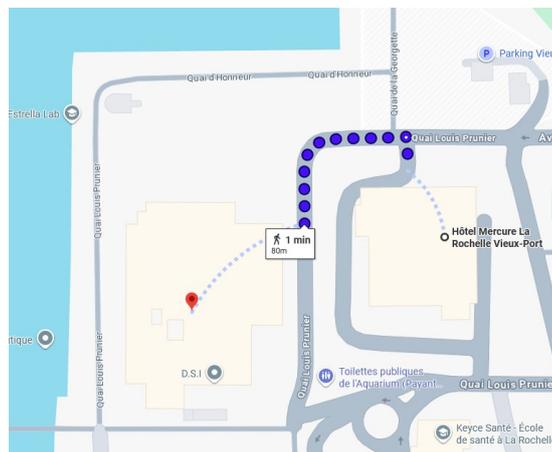
06:30 pm – 10:00 pm

Social Event: Aquarium & Dinner

Visits will start at 6:30pm



1 minute by walk from Mercure Hotel



DAY 2 - 26th March 2026 (Thursday)

08:10 am – 10:00 am

SESSION 2bis: MATERIALS

Chairs: A. Val, P. Couderc

Performance and reliability of aluminium cold plates: A comparison between FSW and Brazing

[L. Dubourg](#), [K. Aznar](#), [V. Pecqueur](#)

Stirweld (France)

Review of strategies to achieve high thermal conductivity encapsulating materials for electronic devices

[R. Khazaka](#), [S. Azzopardi](#)

Safran (France)

Thermal dissipation solution for GaN applications: BIONIC project

[E. Barbier](#), [E. Elrifai](#), [S. Mathieu](#), [M. Coulon](#)

Egide (France)

Advanced Phase Change Thermal Interface Material with Reduced Pump-Out Risk for high reliability thermal management applications

[D. Pudolin](#)

Krayden Europe (Netherlands)

10:00 am – 10:30 am

Coffee Break/ Table top Exhibition

10:30 am – 12:15 pm

SESSION 4bis: 2-PHASE COOLING

Chairs: B. Levrier, D. Saums

Direct two-phase cooling of semiconductors: influence of flow regime and mass flow on local heat transfer coefficient

[A. Loehrmann](#), [O. Crepel \(1\)](#), [E. Videcoq](#), [V. Ayel \(2\)](#), [S. Dutour \(3\)](#)

(1) Airbus SAS, (2) PPrime Institute, CNRS-ENSMA Poitiers (3) LAPLACE, UPS, INPT, CNRS, Université de Toulouse (France)

Pulsating heat pipes for equipment thermal management

[F. Kilinc](#), [M. Sabah \(1\)](#), [V. Ayel](#), [N. Riaud \(2\)](#)

(1) Safran Electronics and Defense, (2) PPRIME INSTITUTE, CNRS – ENSMA – UNIVERSITÉ DE POITIERS (France)

A new regime of stable two-phase heat transport without oscillation in meander shaped low-fill heat pipes

[K. Fumoto](#), [A. Hatamoto](#)

Aoyama Gakuin University (Japan)

Vibration effects on the performance of the heat pipe for aeronautical electronics packaging equipment

[M. Sabah](#)

Safran Electronics and Defense (France)

12:15 pm – 01:40 pm

Lunch

01:50 pm – 02:45 pm

SESSION 5bis: CHARACTERIZATION & TESTS

Chairs: JP. Fradin, A. Reinke

Power-Cycling Test Methodology to Investigate TIM Degradation Under Varying Interface Configurations for High-Performance Computing Using Thermal Test Vehicles

[J. Haseloff](#), [M. Sternberg](#), [D. Wargulski](#), [M. Abo Ras](#)

Berliner Nanotest und Design GmbH

Critical Improvements in Thermal Materials and Characterization Tools

[D. Saums](#)

DS&A LLC (USA)

02:45 pm – 03:40 pm

SESSION 3bis: MODELING & SIMULATIONS
Chairs: JP. Fradin, JY. Soulier

Development of reduced order models (ROM) based on thermal simulations for thermal design of LED products on FR4 boards

[A. Andres \(1\)](#), [V. Shanbhog \(2\)](#), [J. Jiajin Wu \(3\)](#)

(1) Valeo (Spain), (2) Valeo (India), (3) Valeo (China)

Automated toolbox for thermal modelling of printed wiring assemblies

[M. Ali](#), [S. Salvadori \(1\)](#), [V. Singh](#), [A. Battentier \(2\)](#)

(1) SLB (France), (2) SLB (USA)

03:45 pm – 03:50 pm

Closure

Final coffee break and farewell

Exhibition area

Exhibitor Name	Logo
ACCELONIX	
APR Technologies	
ATHERM	
BOYDCORP	
CCI EUROLAM	
dB&DEGREES	
HENKEL	
INVENTEC	
KYOCERA	
METRONELEC	
MICRONOR	
NANOTEST	
RHP	
SERMA Microelectronics	
SIEMENS	
STELIAU	
TEMISTH	
THERMAVANT	
WATTDESIGN	

REGISTRATION FORM ATW THERMAL MANAGEMENT

Final Registration ends on 21st March 2026

Company / Organization:

Name - First Name:

Email:

Address for Invoice:

👉 WORKSHOP FEES INCLUDE:

2 days conference

2 nights Hotel (booked by IMAPS France)

Arrival on 24th March 2026, after 16h00

Departure on 26th March

All lunches and dinners from 24th March 8:00 pm (dinner) to 26th March 2026 4:00 pm

Registration to website: [Imaps \(https://event.imapsfrance.org\)](https://event.imapsfrance.org)

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|---|--------------------|
| <input type="checkbox"/> IMAPS MEMBER | 750 € VAT excluded |
| <input type="checkbox"/> IMAPS NON-MEMBER | 850 € VAT excluded |
| <input type="checkbox"/> SPEAKER/CHAIR/TECHNICAL COMMITTEE | 550 € VAT excluded |
| <input type="checkbox"/> STUDENT | 550 € VAT excluded |
| <input type="checkbox"/> EXHIBITOR | 580 € VAT excluded |
| <input type="checkbox"/> Additional night on 27 th March | 140 € VAT excluded |

(VAT isn't due for non-French resident and/or company registered outside France)

Special Diet: Vegetarian Other _____

Please confirm your attendance to the first day dinner to be held on 24th March by ticking the box or by email to organization.

Reservations to the first day dinner must be submitted by 22nd March, latest.

👉 PAYMENT:

by credit card or even on link: [THERMAL 2026 | Imaps](#)

by bank transfer

IMAPS BANK REFERENCES

IBAN FR 49 3000 2089 4800 0007 9088G 25 BIC CRLYFRPP
LCL CREDIT LYONNAIS VERSAILLES ST LOUIS 16 RUE ROYALE 78000 VERSAILLES France

E-Mail: imaps.france@orange.fr

HOW TO REACH DESTINATION OF CONFERENCE HOTEL



Hotel Mercure Vieux Port
Quai Louis Prunier
17000 La Rochelle - France
46°09'13.7"N 1°08'58.2"W

By Car:

- From Paris: A10 Highway + N11 estimated duration 5h00
- From Bordeaux: A10 + A837 Highway; estimated duration 2h00

By Airplane:

- Airport Bordeaux - Mérignac ([Arrivals and departures of the day | Bordeaux-Merignac Airport](#))
- Airport Rochefort : ([La Rochelle - Ile de Ré airport: Flights, destinations & services](#))

By Train:

La Rochelle station : <https://www.sncf-connect.com/en-en/>

- 14 trains par day from Paris
 - **15h35 Paris-Montparnasse -18h13 La Rochelle** (suggestion)
 - 16h19 Paris Airport CDG2 TGV Roissy – 20h27 La Rochelle (suggestion)
 - **16h59 La Rochelle – 19h34 Paris – Montparnasse** (suggestion)
 -
- 10 Trains per day from Bordeaux
 - 16h52 Bordeaux – 19h28 La Rochelle (suggestion)

Other possibilities from Nantes, Tours,

5-6 minutes by walk to reach Train station from hotel

